



QHBXDFN-8-2x3x0.4mm-NiPdAu						Package Homogeneous Materials				
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	3.38	(mg) Total	Mold Compound	% of Total Weight	42.87
Epoxy Resin A	Trade Secret	Mold Compound	1.286	0.101	12,862		Epoxy Resin A	Trade Secret	3.00	
Epoxy Resin B	Trade Secret	Mold Compound	1.286	0.101	12,862		Epoxy Resin B	Trade Secret	3.00	
Phenol Resin	Trade Secret	Mold Compound	2.144	0.169	21,437		Phenol Resin	Trade Secret	5.00	
Silica (Amorphous) A	60676-86-0	Mold Compound	33.742	2.656	337,417		Silica (Amorphous) A	60676-86-0	78.70	
Silica (Amorphous) B	7631-86-9	Mold Compound	4.287	0.338	42,874		Silica (Amorphous) B	7631-86-9	10.00	
Carbon Black	1333-86-4	Mold Compound	0.129	0.010	1,286		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Bonding Wire	0.112	0.009	1,122	Total100.00				
Palladium	7440-05-3	Bonding Wire	0.004	0.000	36					
Gold	7440-57-5	Bonding Wire	0.000	0.000	4	0.01	(mg) Total	Bonding Wire	% of Total Weight	0.12
Copper	7440-50-8	Lead Frame	49.248	3.877	492,483		Copper	7440-50-8	96.6	
Nickel	7440-02-0	Lead Frame	1.591	0.125	15,909		Palladium	7440-05-8	3.10	
Silicon	7440-21-3	Lead Frame	0.345	0.027	3,447		Gold	7440-57-5	0.35	
Magnesium	7439-95-4	Lead Frame	0.080	0.006	795	Total100.00				
Nickel	7440-02-0	Lead Frame (NiPdAu Plating)	1.591	0.125	15,909					
Palladium	7440-05-3	Lead Frame (NiPdAu Plating)	0.159	0.013	1,591	4.17	(mg) Total	Lead Frame	% of Total Weight	53.03
Gold	7440-57-5	Lead Frame (NiPdAu Plating)	0.016	0.001	159		Copper	7440-50-8	92.87	
Silicon Dioxide	7631-86-9	Die Attach	0.018	0.001	184		Nickel	7440-02-0	3.00	
2-Propenenitrile, polymer with 1,3-butadiene, carboxy-terminated, polymers with bisphenol A and epichlorohydrin	68610-41-3	Die Attach	0.009	0.001	93		Silicon	7440-21-3	0.65	
Phenol-formaldehyde resin	9003-35-4	Die Attach	0.002	0.000	16		Magnesium	7439-95-4	0.15	
Bisphenol A epichlorohydrin polymer	25068-38-6	Die Attach	0.002	0.000	16					
[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	Die Attach	0.000	0.000	3		Nickel	7440-02-0	3.00	
Silicon	7440-21-3	Die	3.950	0.311	39,495		Palladium	7440-05-3	0.30	
TOTALS: 100.007.871,000,000							Gold	7440-57-5	0.03	
7.87 mg Total Mass						Total100.00				
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							Silicon Dioxide	7631-86-9	59.10	
							2-Propenenitrile, polymer with 1,3-butadiene, carboxy-terminated, polymers with bisphenol A and epichlorohydrin	68610-41-3	30.00	
							Phenol-formaldehyde resin	9003-35-4	5.00	
							Bisphenol A epichlorohydrin polymer	25068-38-6	5.00	
							[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	0.90	
						Total100.00				
						0.31	(mg) Total	Die	% of Total Weight	3.95
							Silicon	7440-21-3	100.00	
						7.87	Total	Total	100.00	100.00